04-26-2005

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To the Director of the U.S. Patent and Trade.	2988567 accuments or new address(es) below:		
1. Name of Conveying Party(ies):	2. Name and address of receiving party(ies)		
Manabu SUTOH, Yoshito USHIO, Toyohiko FUJISAWA, and Katsutoshi MINE  Execution Date: January 11, 2005; January 17, 2005; January 17, 2005; January 19, 2005	Name: Dow Corning Toray Silicone Company, Ltd.  Address: 4 <sup>th</sup> Floor, AIG Building  1-3, MarunouchI 1-chome  Chiyoda-Ku, Tokyo 100-0005  JAPAN		
Additional name(s) of conveying party(ies) attached?  Yes No _X	Additional name(s) & address(es) attached: Yes _X_ No		
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4.Application number(s) or patent number(s):  If this document is being filed together with a new application A.  Patent Application No.(s)  B. Patent 10/521,287	tent No(s).		
Additional numbers attached: Ye	es <u>X</u> No		
5. Name and address of party to whom correspondence concerning document should be mailed:	6.Total no. of applications and patents involved One		
Name: <u>David M. LaPrairie</u> Internal Address: <u>Howard &amp; Howard Attorneys, P.C.</u> Street Address: <u>39400 Woodward Avenue, Suite 101</u> City: <u>Bloomfield Hills</u> State: Michigan Zip: 48304-5151			
	7.Total fee (37 CFR 3.41) \$40.00  X Enclosed Authorized to be charged to deposit account		
2005 DBYRNE 00000084 10521287 0021	8. Payment Information  a. Credit Card Last 4 numbers Expiration Date  bDeposit account number 08-2789		
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Name of Person Signing Signature	rvid M. La Pravie April 20, 2005 Date		
Total number of pages including cov	ver sheet, attachments and document: 5		

**REEL: 016483 FRAME: 0779** 

## \_ASSIGNMENT

WHEREAS We, Manabu Sutoh, Yoshito Ushio, Toyohiko Fujisawa, and Katsutoshi Mine have invented certain new and useful improvements in

## SILICONE-BASED ADHESIVE SHEET, METHOD OF BONDING A SEMICONDUCTOR CHIP TO A CHIP ATTACHMENT COMPONENT, AND A SEMICONDUCTOR DEVICE

for which application for United States Letters Patent has been executed by us on this 11th day of

January , 2005; and, 17th day of January, 2005 and 19th day

of January, 2005.					
WHEREAS, DOW CORNING TORAY SILICONE COMPANY, LTD., 4th Floor, AIG					
Building, 1-3, Marunouchl 1-chome, Chiyoda-ku, Tokyo 100-0005, JAPAN, is desirous of acquiring the said					
invention and said application and any and all Letters Patent that may be obtained therefor or thereupon, and all					
reissues and extensions thereof;					
NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that for and in					
consideration of the sum of 100 Yen, and other good and valuable considerations, to us in hand					
paid by the said DOW CORNING TORAY SILICONE COMPANY, LIMITED, the receipt of which is hereby					
acknowledged, we have sold, assigned, transferred and set over and by these presents do sell, assign, transfer					
and set over unto the said DOW CORNING TORAY SILICONE COMPANY, LTD., its successors, and					
assigns, the full and exclusive right, title and interest in and to said invention and said application for Letters					
Patent of the United States therefor, and in and to any Divisions and Continuations thereof and in and to any and					
all United States Letters Patent and reissues and extensions thereof that may be issued for the said invention, to					
have and to hold for its own use and behoof and the use and behoof of its successors and assigns as fully and					
entirely as the same might be enjoyed by us if this sale and assignment had not been made; and					

HEREBY AUTHORIZE and request the Commissioner of Patents and Trademarks to issue the said Letters Patent and any reissues and extensions thereof to the said DOW CORNING TORAY SILICONE COMPANY, LTD. as assigns of the entire right, title and interest in and to the said invention and said application and Letters Patent issued therefor or thereupon; and

HEREBY AGREE to execute all instruments and documents within our power which may be necessary for the carrying out of this assignment in full; and to execute any divisional or continuing application or applications which may be necessary or proper to obtain full protection on the invention hereby assigned; and to execute any and all supplemental oaths and preliminary statements should the same be proper and necessary in the prosecution of the aforesaid applications; and

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## HEREBY FURTHER ASSIGN unto the said DOW CORNING TORAY SILICONE

COMPANY, LIMITED, its successors, and assigns, the whole right, title and interest in and to the invention disclosed in the said application throughout all countries foreign to the United States, and do hereby ratify any acts of the said DOW CORNING TORAY SILICONE COMPANY, LIMITED, its successors and assigns, in applying for patents therefor in its own name in countries where such procedure is proper and do agree to execute applications for said invention in the several countries where it is necessary that the same be executed by the inventors, and to execute assignments of such applications and the patents to be obtained therefor to the said DOW CORNING TORAY SILICONE CO., LTD., its successors and assigns.

IN WITNESS WHEREOF I have hereunto set my hand

Manalu Sutch	January 11, 2005
Manabu Sutoh	Date
This is to certify that Manabu Sutoh has sig	ned this document in my presence this11thday of
January , 2005 , Japa	
Signature of Witness	
Hiromi Fujita	
IN WITNESS WHEREO	F I have hereunto set my hand
Yoshito Ushio	January 17, 2005
Yoshito Ushio	Date
This is to certify that Yoshito Ushio has sign	ned this document in my presence this 17th day of
January , 2005 , Japa	n.
January , 2005 , Japa	
Signature of Witness	
Hiromi Fujita	
IN WITNESS WHEREO	F I have hereunto set my hand
Toyohiko Fujisawa	January 17, 2005
Toyohiko Fujisawa	Date
This is to certify that Toyohiko Fujisawa ha	s signed this document in my presence this17thday or
	n.
January , 2005 , Japa	
Signature of Witness	
Hiromi Fujita	

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## IN WITNESS WHEREOF I have hereunto set my hand

Materialia	Mine	<del></del>	January 19, 2005	<del></del>
Katsutoshi Mine			Date	
This is to certify that	ıt Katsutoshi Mir	ne has signed	ed this document in my presence this 19th	day of
January	,2005	, Japan.		
_ Hiromi	Fusto			
Signature of Witness	is			
Hiromi Fujita			•	

PATENT
RECORDED: 04/22/2005 REEL: 016483 FRAME: 0782